Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A-0410-02** DATE: 10/5/2004

Product Affected: All IDT Products (see attached list)

Date Effective: 1/4/2005

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☒ Product Mark
- ☐ Back Mark
- ☐ Date Code
- ☐ Other

Contact: Geoffrey Cortes
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Attachment:: ☒ Yes ☐ No

Samples: N/A

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ☐ Manufacturing Site
- ☐ Data Sheet
- ☒ Other (Marking Logo)

Change IDT Marking Logo (Top Mark)

From: IDT To: IDT

RELIABILITY/QUALIFICATION SUMMARY:

This change has no impact on product performance, characteristics or reliability.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ ☐ ***Approval for shipments prior to effective date.***

Name/Date: _____ E-Mail Address: _____

Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____

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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: A-0410-02

PCN Type: IDT Marking Logo (Top Mark)

Data Sheet Change: None

Detail of Change:

All IDT Products with packages that are greater or equal to 10x10 mm in package dimension (L x W) will be marked with new IDT Gridless Wafer Logo.
Packages that are less then 10x10 mm in package dimension (L x W) will continue to be marked with existing IDT Block Logo.
Parts marked with the existing logo and revised logo may be mixed in a shipment.

Please see attached list of packages that will be marked with new IDT Gridless Wafer Logo.

Package Type	Package Type	Package Type	Package Type	Package Type
CABGA 100	PBGA 196	PLCC 32	SOJ 32	CPGA 208
CABGA 144	PBGA 208	PLCC 44	SOJ 36	CPGA 223
CABGA 256	PBGA 240	PLCC 52	SOJ 44	CPGA 296
FPBGA 165	PBGA 256	PLCC 68	TQFP 100	CPGA 447
FCBGA 372	PBGA 260	PLCC 84	TQFP 120	CPGA 68
FCBGA 472	PBGA 272	PQFP 100	TQFP 128	CPGA 84
FCBGA 616	PBGA 324	PQFP 128/132	TQFP 144	CQSOP 84
FCBGA 900	PBGA 388	PQFP 144	TQFP 44	LCC 32
FPBGA 100	PBGA 416	PQFP 160	TQFP 64	LCC 44
FPBGA 144	PBGA 481	PQFP 208	TQFP 80	LCC 48
FPBGA 208	PBGA 525	PQFP 44	TSOP 32	LCC 52
MQUAD 128	PBGA 680	PQFP 52	TSOP 44	LCC 68
MQUAD 160	PBGA 74	PQFP 64	VFQFP 68	SIDE BRAZE 24
MQUAD 208	PBGA 820	PQFP 80	CERDIP 24	SIDE BRAZE 28
MQUAD 84	PDIP 24	SBGA 272	CERDIP 28	SIDE BRAZE 32
PBGA 119	PDIP 28	SBGA 304	CERDIP 40	SIDE BRAZE 40
PBGA 121	PDIP 32	SBGA 352	CPGA 108	SIDE BRAZE 48
PBGA 144	PDIP 40	SBGA 372	CPGA 144	SIDE BRAZE 64
PBGA 156	PDIP 48	SBGA 854	CPGA 175	SIDE BRAZE 68
PBGA 160	PLCC 28	SOJ 28	CPGA 179	TOP BRAZE 64